



Symbol	Hit Count	Tool Size	Plated	Hole Type
C	8	0.508mm (20mil)	PTH	Round
B	65	0.711mm (28mil)	PTH	Round
A	3	1mm (39.37mil)	PTH	Round
	76 Total			

Drill Table
 DRILL TOLERANCES: FOR PTH +/-3MILS
 FOR NPTH +/-2MILS

Layer Name	Order Document	Copper Thickness	Dielectric Material
Top Solder Mask	<.GTS		Solder Resist
Top Layer	<.GTL	0.0356mm	FR-4
Bottom Layer	<.GBL	0.0356mm	
Bottom Solder Mask	<.GBS		Solder Resist

DESIGN INFORMATION
 BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
 100MM X 100MM
 Number of Layers : 2
 MIN. TRACK WIDTH: 10_MIL
 MIN. CLEARANCE: 8_MIL
 MIN. VIA PAD SIZE: 10_MIL
 MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5_MIL HOLES +/- 3_MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI PC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI PC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 COPPER THICKNESS (FINISHED):
 OUTER: 1.4ML (1oz) 2ML (1.4oz) 2.8ML (2oz)
 INNER SIGNAL: 1.4ML (1oz) 2.8ML (2oz) N/A
 DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____
 BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____
 SURFACE FINISH: IMMERSION GOLD (ENIG) ENEPiG
 MM. TIN/SILVER OR EQUIV OTHER _____
 ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE
 CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI PC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES VIA TENCING: NONE REQUIRED
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S UL: RAL METAL SILK



PROJECT TITLE: TIDA-00227 - ISE3033	
DESIGNED FOR: Public Release	
FILE NAME: TIDA-00227	
ENGINEER: Sunil D	LAYOUT BY:
SCALE: 0.67	ALTIM DESIGNER VERSION: 10.0.0.27009

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00227	REV: A1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TIDA-00227		
PLOT NAME = Fabrication Drawing	GENERATED : 8/28/2014 11:07:43 AM	TEXAS INSTRUMENTS	

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